

General Description

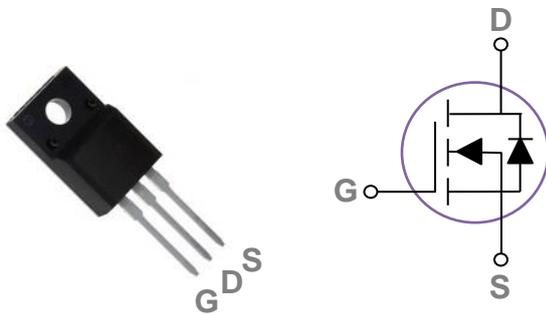
These N-Channel enhancement mode power field effect transistors are using Super Junction technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply

| | | |
|-------|-------|-----|
| BVDSS | RDSON | ID |
| 500V | 0.22Ω | 21A |

Features

- 21A,500V, $R_{DS(ON)} = 0.22\Omega @ V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

TO220F Pin Configuration



Applications

- High efficient switched mode power supplies
- LED Lighting
- Adapter/charger

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

| Symbol | Parameter | Rating | Units |
|------------------|--|------------|-------|
| V _{DS} | Drain-Source Voltage | 500 | V |
| V _{GS} | Gate-Source Voltage | ±30 | V |
| I _D | Drain Current – Continuous (T _C =25°C) (Chip Limitation) | 21 | A |
| | Drain Current – Continuous (T _C =100°C) (Chip Limitation) | 13.3 | A |
| I _{DM} | Drain Current – Pulsed ¹ | 84 | A |
| EAS | Single Pulse Avalanche Energy ² | 370 | mJ |
| IAS | Single Pulse Avalanche Current ² | 6.6 | A |
| P _D | Power Dissipation (T _C =25°C) | 400 | W |
| | Power Dissipation – Derate above 25°C | 3.22 | W/°C |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| 5T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction to ambient | --- | 62.5 | °C/W |
| R _{θJC} | Thermal Resistance Junction to Case | --- | 5 | °C/W |

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------|--------------------------------|--|------|------|-----------|---------|
| BV_{DS} | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=250\mu A$ | 500 | --- | --- | V |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=500V, V_{GS}=0V, T_J=25^\circ\text{C}$ | --- | --- | 25 | μA |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 30V, V_{DS}=0V$ | --- | --- | ± 100 | nA |

On Characteristics

| | | | | | | |
|--------------|-----------------------------------|-------------------------------|-----|-----|------|----------|
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance | $V_{GS}=10V, I_D=10.5A$ | --- | --- | 0.22 | Ω |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}, I_D=250\mu A$ | 2.5 | --- | 4.5 | V |

Dynamic and switching Characteristics

| | | | | | | |
|--------------|-------------------------------------|--|-----|------|-----|----|
| Q_g | Total Gate Charge ^{2, 3} | $V_{DS}=50V, V_{GS}=10V, I_D=1.3A$ | --- | 120 | --- | nC |
| Q_{gs} | Gate-Source Charge ^{2, 3} | | --- | 10 | --- | |
| Q_{gd} | Gate-Drain Charge ^{2, 3} | | --- | 40 | --- | |
| $T_{d(on)}$ | Turn-On Delay Time ^{2, 3} | $V_{DD}=30V, V_{GS}=10V, R_G=25\Omega$ $I_D=0.5A$ | --- | 70 | --- | ns |
| T_r | Rise Time ^{2, 3} | | --- | 180 | --- | |
| $T_{d(off)}$ | Turn-Off Delay Time ^{2, 3} | | --- | 330 | --- | |
| T_f | Fall Time ^{2, 3} | | --- | 200 | --- | |
| C_{iss} | Input Capacitance | $V_{DS}=25V, V_{GS}=0V, F=1\text{MHz}$ | --- | 1030 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 850 | --- | |
| C_{rfs} | Reverse Transfer Capacitance | | --- | 78 | --- | |

Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|----------|--------------------------------------|--|------|------|------|---------|
| I_S | Continuous Source Current | $V_G=V_D=0V, \text{Force Current}$ | --- | --- | 21 | A |
| I_{SM} | Pulsed Source Current | | --- | --- | 42 | A |
| V_{SD} | Diode Forward Voltage | $V_{GS}=0V, I_S=21A, T_J=25^\circ\text{C}$ | --- | --- | 1.4 | V |
| t_{rr} | Reverse Recovery Time ² | $V_{GS}=0V, I_S=21A, di/dt=100A/\mu s,$ | --- | 420 | --- | ns |
| Q_{rr} | Reverse Recovery Charge ² | $T_J=25^\circ\text{C}$ | --- | 7.1 | --- | μC |

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=50V, V_{GS}=10V, L=17\text{mH}, I_{AS}=6.6A, R_G=25\Omega, \text{Starting } T_J=25^\circ\text{C}$.
3. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

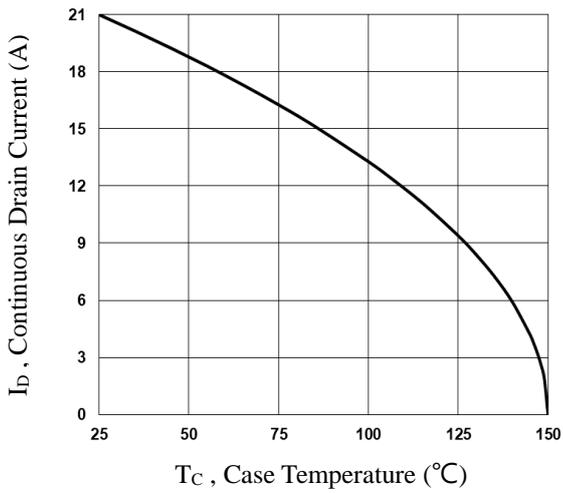


Fig.1 Continuous Drain Current vs. T_c

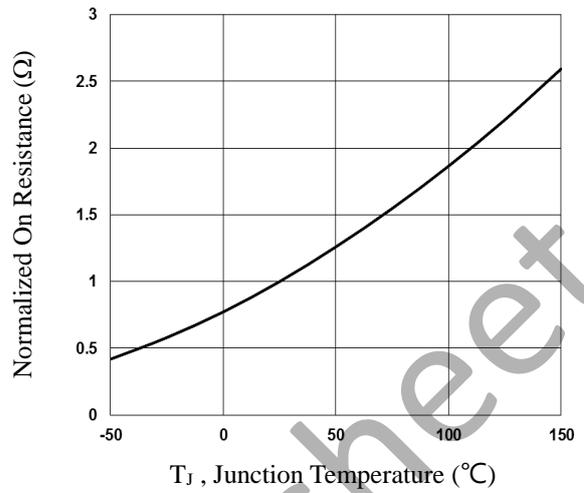


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

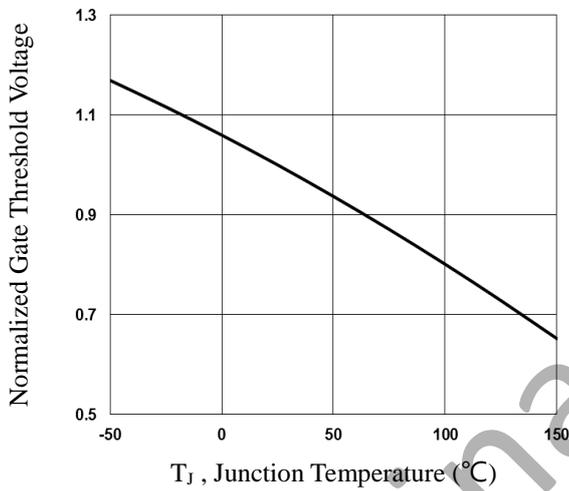


Fig.3 Normalized V_{th} vs. T_j

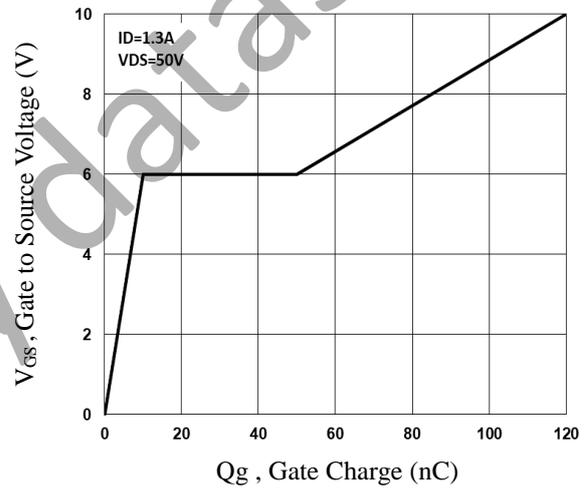


Fig.4 Gate Charge Waveform

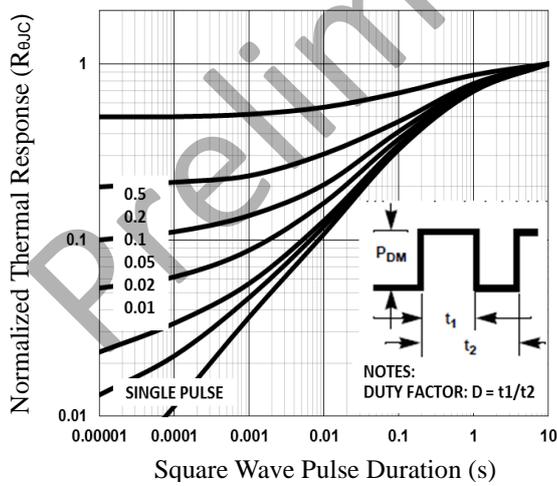


Fig.5 Normalized Transient Impedance

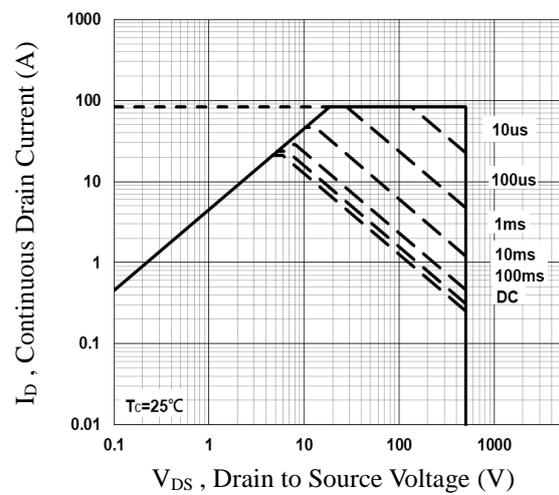


Fig.6 Maximum Safe Operation Area

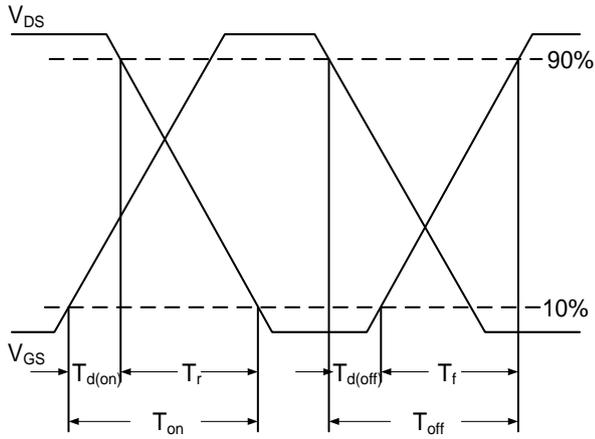


Fig.7 Switching Time Waveform

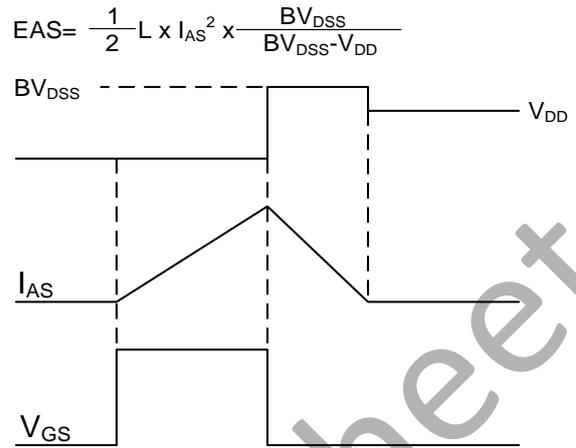
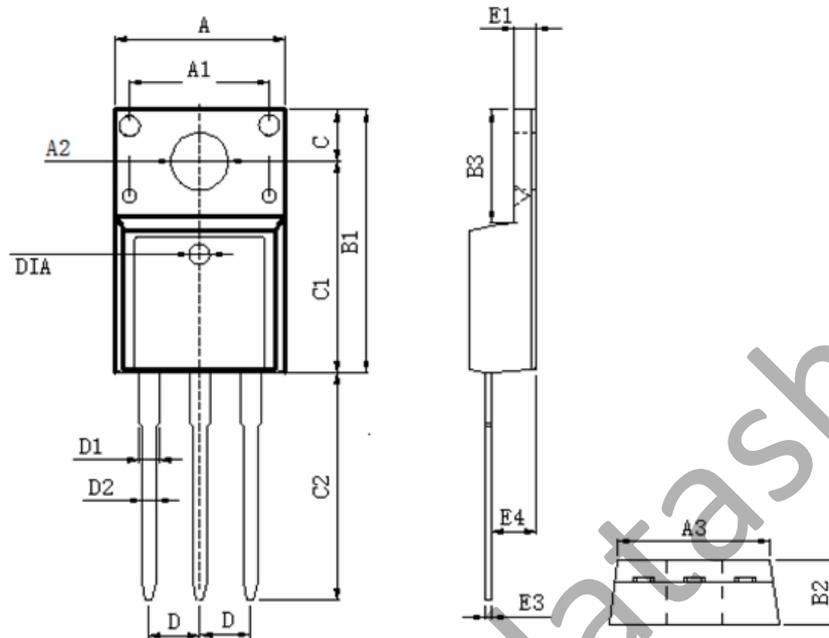


Fig.8 EAS Waveform

Preliminary datasheet

TO220F PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|--------------|----------------------|----------------|
| | MAX | MIN | MAX | MIN |
| A | 10.460 | 9.860 | 0.412 | 0.388 |
| A1 | 7.100 | 6.900 | 0.280 | 0.272 |
| A2 | 3.500 | 3.100 | 0.138 | 0.122 |
| A3 | 9.900 | 9.500 | 0.390 | 0.374 |
| B1 | 16.170 | 15.570 | 0.637 | 0.613 |
| B2 | 4.900 | 4.500 | 0.193 | 0.177 |
| B3 | 6.880 | 6.480 | 0.271 | 0.255 |
| C | 3.500 | 3.100 | 0.138 | 0.122 |
| C1 | 12.870 | 12.270 | 0.507 | 0.483 |
| C2 | 13.380 | 12.580 | 0.527 | 0.495 |
| D | 2.590 | 2.490 | 0.102 | 0.098 |
| D1 | 1.470 | 1.070 | 0.058 | 0.042 |
| D2 | 0.900 | 0.700 | 0.035 | 0.028 |
| E1 | 2.740 | 2.340 | 0.108 | 0.092 |
| E3 | 0.600 | 0.400 | 0.024 | 0.016 |
| E4 | 2.960 | 2.560 | 0.117 | 0.101 |
| DIA | Φ1.5 TYP. | deep0.1 TYP. | Φ0.059 TYP. | deep0.004 TYP. |